

## HIGH CURRENT, HIGH PERFORMANCE, LOW VOLTAGE PNP TRANSISTOR

### Features

- VERY LOW COLLECTOR TO EMITTER SATURATION VOLTAGE
- D.C. CURRENT GAIN,  $h_{FE} > 100$
- 5 A CONTINUOUS COLLECTOR CURRENT
- SOT-223 PLASTIC PACKAGE FOR SURFACE MOUNTING CIRCUITS
- AVAILABLE IN TAPE & REEL PACKING
- IN COMPLIANCE WITH THE 2002/93/EC EUROPEAN DIRECTIVE

### Applications

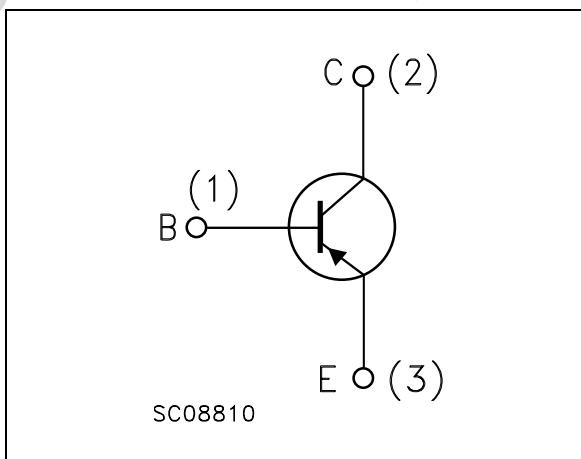
- POWER MANAGEMENT IN PORTABLE EQUIPMENT
- VOLTAGE REGULATION IN BIAS SUPPLY CIRCUITS
- SWITCHING REGULATOR IN BATTERY CHARGER APPLICATIONS
- HEAVY LOAD DRIVER

### Description

The device is manufactured in low voltage PNP Planar Technology by using a "Base Island" layout. The resulting transistor shows exceptional high gain performance coupled with very low saturation voltage.



**Internal Schematic Diagram**



### Order Codes

Part Number	Marking	Package	Packing
STN888	N888	SOT-223	Tape & Reel

# 1 Absolute Maximum Ratings

**Table 1. Absolute Maximum Rating**

Symbol	Parameter	Value	Unit
$V_{CBO}$	Collector-Base Voltage ( $I_E = 0$ )	-45	V
$V_{CEO}$	Collector-Emitter Voltage ( $I_B = 0$ )	-30	V
$V_{EBO}$	Emitter-Base Voltage ( $I_C = 0$ )	-6	V
$I_C$	Collector Current	-5	A
$I_{CM}$	Collector Peak Current ( $t_P < 5\text{ms}$ )	-10	A
$P_{TOT}$	Total dissipation at $T_c = 25^\circ\text{C}$	1.6	W
$T_{stg}$	Storage Temperature	-65 to 150	$^\circ\text{C}$
$T_J$	Max. Operating Junction Temperature	150	$^\circ\text{C}$

**Table 2. Thermal Data**

Symbol	Parameter	Value	Unit
$R_{thj-amb}$	Thermal Resistance Junction-Ambient Max	78	$^\circ\text{C}/\text{W}$

## 2 Electrical Characteristics

( $T_{CASE} = 25^\circ\text{C}$ ; unless otherwise specified)

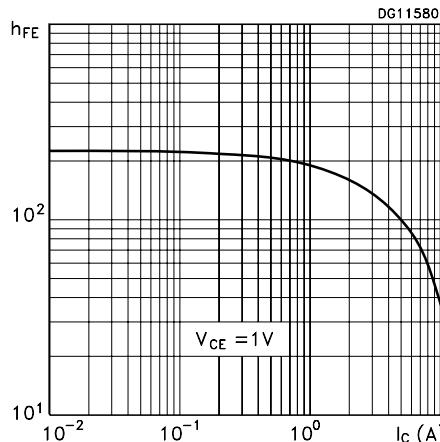
**Table 3. Electrical Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_{CBO}$	Collector Cut-off Current ( $I_E = 0$ )	$V_{CB} = -30\text{V}$ $V_{CB} = -30\text{V}$ $T_C = 100^\circ\text{C}$			-10 -100	$\mu\text{A}$ $\mu\text{A}$
$I_{EBO}$	Emitter Cut-off Current ( $I_C = 0$ )	$V_{EB} = -6\text{V}$			-10	$\mu\text{A}$
$V_{(BR)CEO}$ <i>Note: 1</i>	Collector-Emitter Breakdown Voltage ( $I_B = 0$ )	$I_C = -10\text{mA}$	-30			$\text{V}$
$V_{(BR)CBO}$	Collector-Base Breakdown Voltage ( $I_E = 0$ )	$I_C = -100\mu\text{A}$	-45			$\text{V}$
$V_{(BR)EBO}$	Emitter-Base Breakdown Voltage ( $I_C = 0$ )	$I_E = -100\mu\text{A}$	-6			$\text{V}$
$V_{CE(sat)}$ <i>Note: 1</i>	Collector-Emitter Saturation Voltage	$I_C = -500\text{mA}$ $I_B = -5\text{mA}$ $I_C = -2\text{A}$ $I_B = -50\text{mA}$ $I_C = -5\text{A}$ $I_B = -250\text{mA}$ $I_C = -6\text{A}$ $I_B = -250\text{mA}$ $I_C = -8\text{A}$ $I_B = -400\text{mA}$ $I_C = -10\text{A}$ $I_B = -500\text{mA}$			-0.15 -0.35 -0.70 -0.7 -1.0 -1.2	$\text{V}$ $\text{V}$ $\text{V}$ $\text{V}$ $\text{V}$ $\text{V}$
$V_{BE(sat)}$ <i>Note: 1</i>	Base-Emitter Saturation Voltage	$I_C = -2\text{A}$ $I_B = -50\text{mA}$ $I_C = -6\text{A}$ $I_B = -250\text{mA}$			-1.1 -1.2	$\text{V}$ $\text{V}$
$h_{FE}$ <i>Note: 1</i>	DC Current Gain	$I_C = -10\text{mA}$ $V_{CE} = -1\text{V}$ $I_C = -500\text{mA}$ $V_{CE} = -1\text{V}$ $I_C = -5\text{A}$ $V_{CE} = -1\text{V}$ $I_C = -5\text{A}$ $V_{CE} = -1\text{V}$ $t_j = 100^\circ\text{C}$ $I_C = -8\text{A}$ $V_{CE} = -1\text{V}$ $I_C = -10\text{A}$ $V_{CE} = -1\text{V}$	120 100 70 100 55 35	200 200 100 100 55 35		
$t_d$ $t_r$ $t_s$ $t_f$	INDUCTIVE LOAD Delay Time Rise Time Storage Time Fall Time	$I_C = -3\text{A}$ $V_{CC} = -20\text{V}$ $I_{B1} = -I_{B2} = -60\text{mA}$ (see Figure 7)		180 160 250 80	220 210 300 100	ns ns ns ns

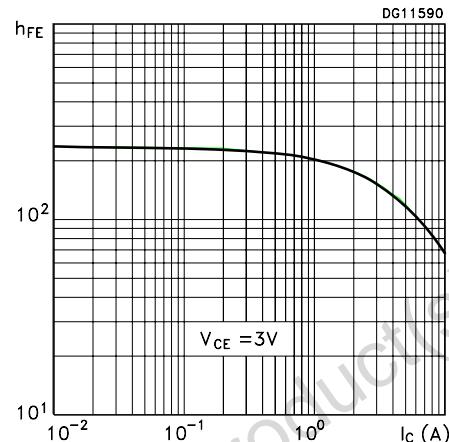
*Note: 1 Pulsed duration = 300  $\mu\text{s}$ , duty cycle  $\leq 1.5\%$ .*

## 2.1 Typical Characteristics

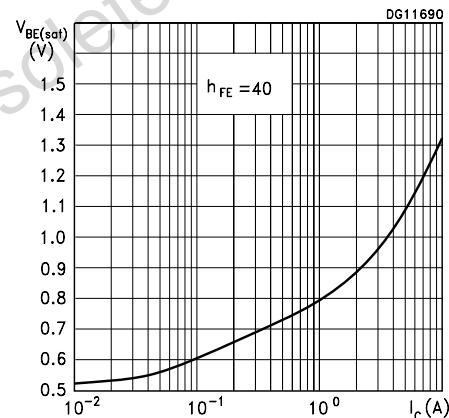
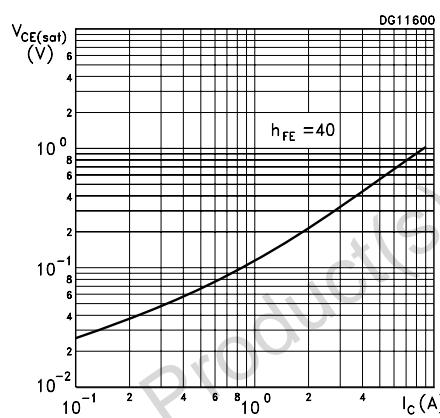
**Figure 1. DC Current Gain**



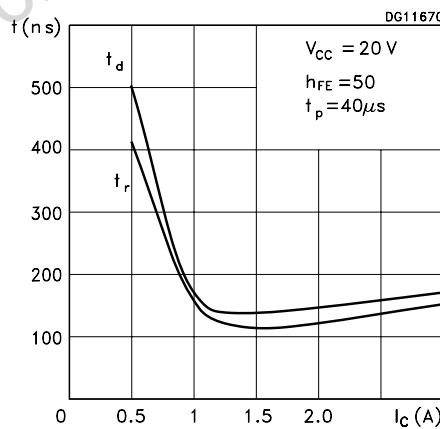
**Figure 2. DC Current Gain**



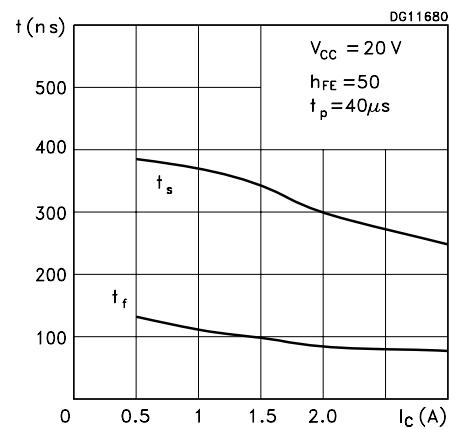
**Figure 3. Collector-Emitter Saturation Voltage**    **Figure 4. Base-Emitter Saturation Voltage**



**Figure 5. Switching Times Resistive Load**

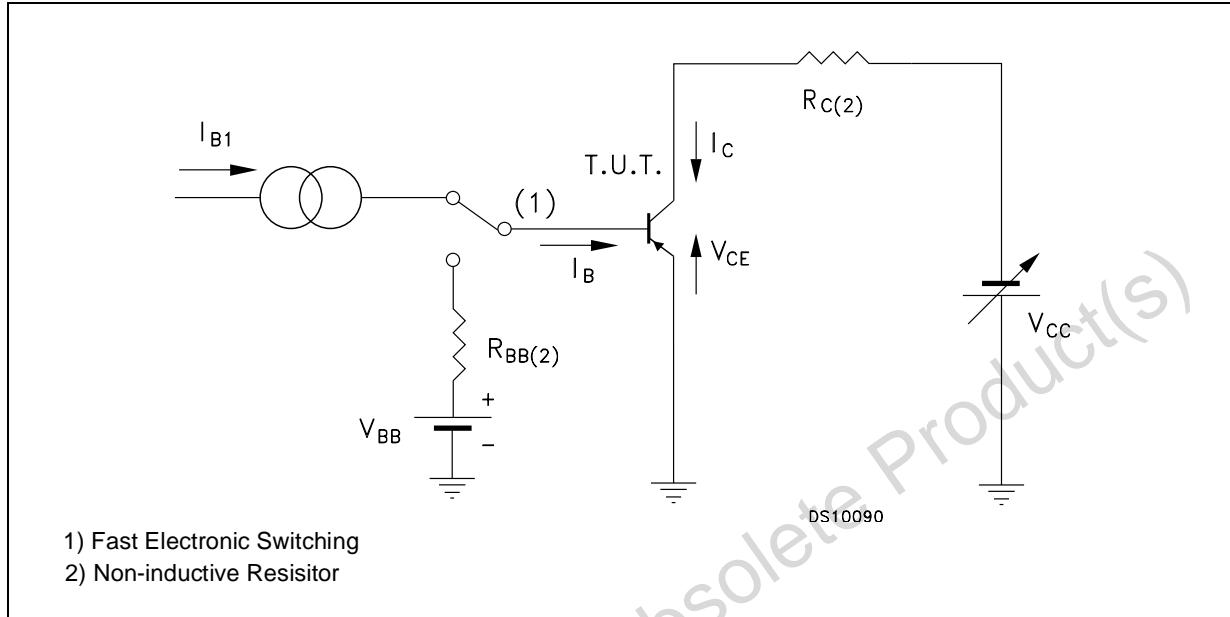


**Figure 6. Switching Times Resistive Load**



### 3 Test Circuits

Figure 7. Resistive Load Switching Test Circuit

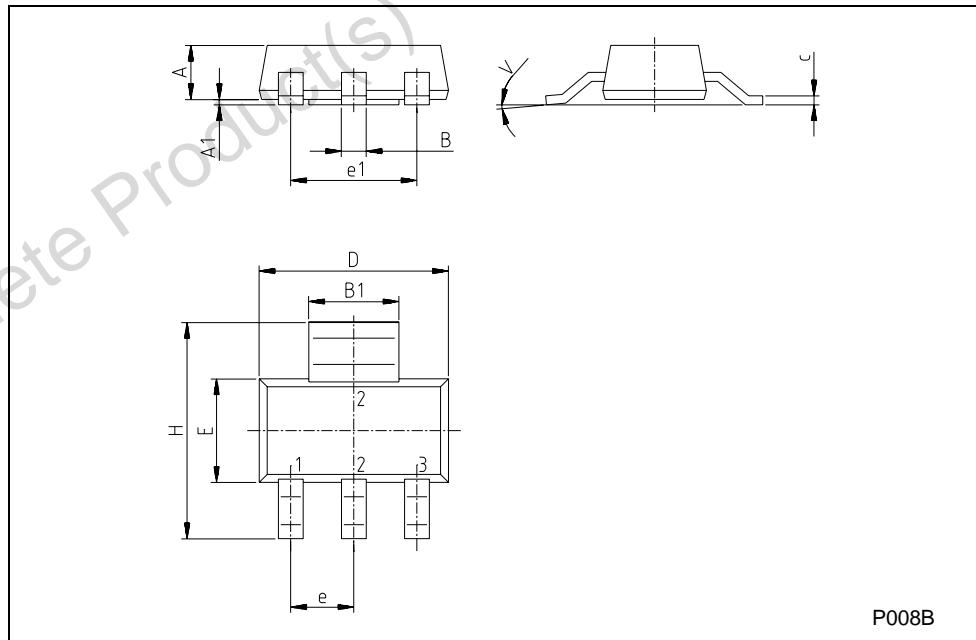


## 4 Package Mechanical Data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com)

**SOT-223 MECHANICAL DATA**

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.80			0.071
B	0.60	0.70	0.80	0.024	0.027	0.031
B1	2.90	3.00	3.10	0.114	0.118	0.122
c	0.24	0.26	0.32	0.009	0.010	0.013
D	6.30	6.50	6.70	0.248	0.256	0.264
e		2.30			0.090	
e1		4.60			0.181	
E	3.30	3.50	3.70	0.130	0.138	0.146
H	6.70	7.00	7.30	0.264	0.276	0.287
V			10°			10°
A1		0.02				



## 5 Revision History

Date	Revision	Changes
03-Aug-2005	1	Initial release.

Obsolete Product(s) - Obsolete Product(s)

Obsolete Product(s) - Obsolete Product(s)

Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a registered trademark of STMicroelectronics.  
All other names are the property of their respective owners

© 2005 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan -  
Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

[www.st.com](http://www.st.com)

